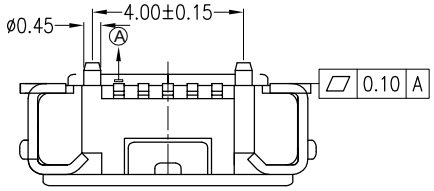
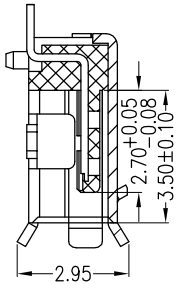
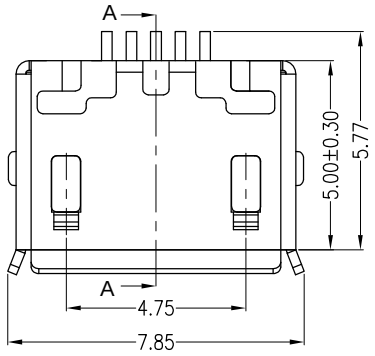
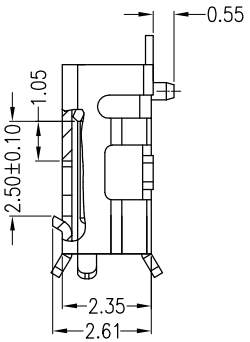
| REV. | ECN NO | LOCATIONS | DESCRIPTION | DATE |
|---|---|---|---|---|
| | | | | |

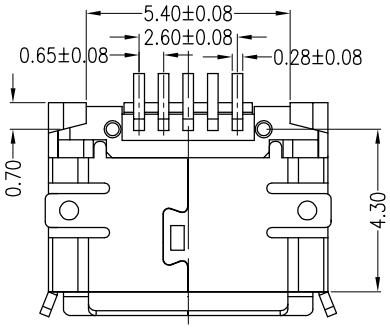


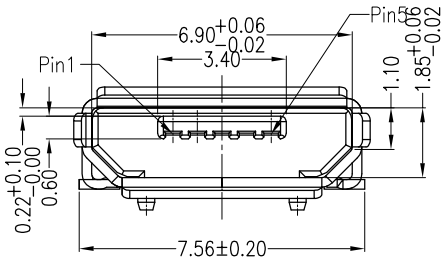



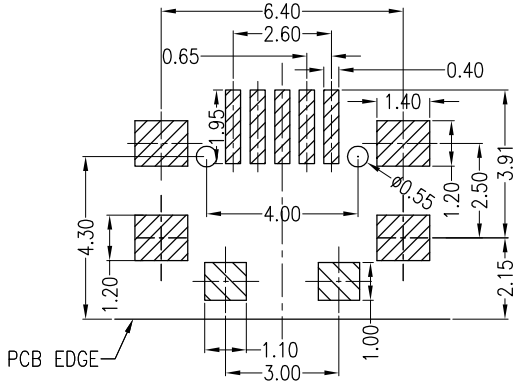

SECTION A-A'




RECOMMANDED PCB LAYOUT

PCB图仅供参考

Note:
1.Material:
- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:
- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min
- 2.7 Temperature range: -30°C~80°C

外壳材质
1:C2680R-H

外壳电镀
1:N50u''
2:雾T50u''
3:N+Au1u''(脚)
4:Au1u''

端子电镀 01:Au1u'';02:Au1.5u'';03:Au3u''
05:Au5u'' ;10:Au10u'';15:Au15u'';30:Au30u''
主体颜色 B:黑色
主体材质 1:LCP
端子材质 4:C5191R-EH

| | | | |
|---|---|---|---|
| PART NO: USB-F06505-BT014 | | MATERAL: SEE NOTE | WFD CONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD |
| MODEL NO: XX | | FINSH: SEE NOTE | |
| UNIT: MM | SIZE: A4 | COLOR: SEE NOTE | TITLE: Micro usb 5S B Type (SMT)有柱有孔型锡脚加长0.75 |
| TOLERANCE UNSPECIFIED<br>.x 0.15<br>.xx 0.10<br>.xxx 0.05<br>Ang. 1° | | DR: LIU MIAO<br>CHK: SIMON<br>APP: DAVID | DWG NO: A021 REV: A<br>SCALE: 5:1 DATE: 2012.05.17 |